Compound Semiconductor Materials Europe TC Chapter

Meeting Summary and Minutes

SEMICON Europa
Thursday, November 20, 2025
9:00-10:30 CET
Internationales Congress Center München, Germany

TC Chapter Announcements

Next TC Chapter Meeting

April 14, 2026

16:00-18:00 CEST

Online via Virtual Conference

Table 1 Meeting Attendees

Italics indicate virtual participants

Co-Chairs: Arnd Weber (SiCrystal), Christian Kranert (Fraunhofer IISB)
SEMI Staff: Michelle Sun

Company	*Last*	*First*	*Company*	*Last*	*First*
Anyifa Semiconductor	*Zhang*	*Jack*	SEMI	Sun	Michelle
Bruker Corporation	*Lafford*	*Tamzin*	SEMI	*Yoshida*	*Akiko*
Certie	*Ko*	*Kennis*	SiCrystal Gmbh	Weber	Arnd
Fraunhofer IISB	*Kranert*	*Christian*	SiCrystal Gmbh	*Dietrich*	*Marc*
GlobalWafers	Sanna	Cristina	SOITEC	*Olivier*	*Bonnin*
Infineon	Broxtermann	Mike	SOITEC	*Cela*	*Enrica*
Munich University of Applied Sciences	Christian	Hans	TSMC	*Tsou*	*Tsung-Yu*
Scientific Visual SA	*Cheze*	*Caroline*			

Table 2 Leadership Changes

WG/TF/SC/TC Name	*Previous Leader*	*New Leader*
None		

Table 3 TC Chapter Structure Changes

Previous WG/TF/SC Name	*New WG/TF/SC Name or Status Change*
None	

Table 4 Ballot Results

Document #	*Document Title*	*Committee Action*
None		

#1 **Passed** ballots and line items will be submitted to the ISC Audit & Review Subcommittee for procedural review.

#2 **Failed** ballots and line items were returned to the originating task forces for re-work and re-balloting or abandoning.

Table 5 Ratification Ballot Results

Document #	*Document Title*	*ISC A&R Action*	*A&R Forms*
None			

Note 1: **Passed** Ratification ballots will be submitted to SEMI publication for final processing.

Note 2: **Failed** Ratification ballots were returned to the originating task forces for re-work and re-balloting or abandoning.

Table 6 Activities Approved by the GCS between meetings of the TC Chapter

#	*Type*	*SC/TF/WG*	*Details*
None			

Table 7 Authorized Activities

Listing of all revised or new SNARF(s) approved by the Originating TC Chapter.

#	*Type*	*SC/TF/WG*	*Details*
7416	SNARF	5-year Review TF	Reapproval of SEMI M82-0820, Test Method for the Carbon Acceptor Concentration in Semi-Insulating Gallium Arsenide Single Crystals by Infrared Absorption Spectroscopy
7417	SNARF	Silicon Carbide TF	Line-Item Revision to SEMI M55-0921, Specification for Polished Monocrystalline Silicon Carbide Wafers

#1 SNARFs and TFOFs are available for review on the SEMI Web site at:
http://downloads.semi.org/web/wstdsbal.nsf/TFOFSNARF

Table 8 Authorized Ballots

#	*When*	*TF*	*Details*
7111	Cycle 1 or 2-2026	SiC Material and Wafer Specification TF	Revision of SEMI M81-0418, Guide to Defects Found in Monocrystalline Silicon Carbide Substrates
7416	SNARF	5-year Review TF	Reapproval of SEMI M82-0820, Test Method for the Carbon Acceptor Concentration in Semi-Insulating Gallium Arsenide Single Crystals by Infrared Absorption Spectroscopy

Table 9 SNARF(s) Granted a One-Year Extension

#	*TF*	*Title*	*Expiration Date*
7111	SiC Material and Wafer Specification TF	Revision of SEMI M81-0418, Guide to Defects Found in Monocrystalline Silicon Carbide Substrates	11/20/2026

Table 10 SNARF(s) Cancelled

#	*TF*	*Title*
None		

Table 11 Standard(s) to receive Inactive Status

Standard Designation	*Title*
None	

Table 12 New Action Items

Item #	*Assigned to*	*Details*
None		

Table 13 Previous Meeting Action Items

Item #	*Assigned to*	*Details*
None		

1 Welcome, Reminders, and Introductions

Dr. Arnd-Dietrich Weber (SiCrystal Gmbh) called the meeting to order at 9:04. The meeting reminders on antitrust issues, intellectual property issues and holding meetings with international attendance were reviewed. Attendees introduced themselves.

Attachment: Required Meeting Elements March 2024

2 Review of Previous Meeting Minutes

The TC Chapter reviewed the minutes of the previous meeting.

Motion: Approve the minutes as written
By / 2nd: By: Christian Kranert / Fraunhofer IISB
Second: Hans Christian Alt / Munich University of Applied Sciences
Discussion: None
Vote: 3-Y 0-N

Attachment: CSM EU TC Minutes 04012025

3 Liaison Reports

3.1 *Compound Semiconductor Materials Japan TC Chapter*

Michelle Sun (SEMI) reported for the Compound Japan TC Chapter. Of note:

- Last meeting
  - Monday, June 30, 2025
  - SEMI Japan, Tokyo, Japan + OVTCCM (Hybrid)
- Next meeting
  - Thursday, December 18, 2025
  - Tokyo Big Sight, Tokyo, Japan + OVTCCM (Hybrid) in conjunction with SEMICON Japan 2025
- Ballot Results
  - 7211A, Line Item Revision to SEMI M92-0824, Specification for 4H-SiC Homoepitaxial Wafer
    - LI 1 = Passed
    - LI 2 = Passed
- Task Force Highlights
  - Silicon Carbide Substrate Liaison Task Force

        - Continue to communicate with the Silicon Carbide Substrate Task Force under the Compound Semiconductor Materials China TC Chapter, for better development of Doc.# 6767A, New Standard: Test Method for Flatness of Silicon Carbide Wafers by Optical Interference as well as Doc.#6769C, New Standard: Test Method for Residual Stress of Silicon Carbide Wafers by Photoelastic.
        - Concerns were expressed regarding the relationship between above activities and newly prepared SNARFs.
    - SiC Epitaxial Wafer Liaison Task Force
        - Doc.#7211A, Line Item Revision to SEMI M92 was submitted for Cycle 4, 2025 and both Line Items 1 & 2 passed TC review and subsequent procedural review by the ISC A&R SC.
        - Pending publication.
        - Considering to include 200.0 mm 4H-SiC epitaxial wafers in SEMI M92, Specification for 4H-SiC Homoepitaxial Wafer by submitting another SNARF.

Attachment: CSM_JA TC Chapter Liaison Report_October 2025_R1

3.2 *Compound Semiconductor Materials China TC Chapter*

Michelle Sun (SEMI) reported for the Compound Semiconductor Materials China TC Chapter. Of note:

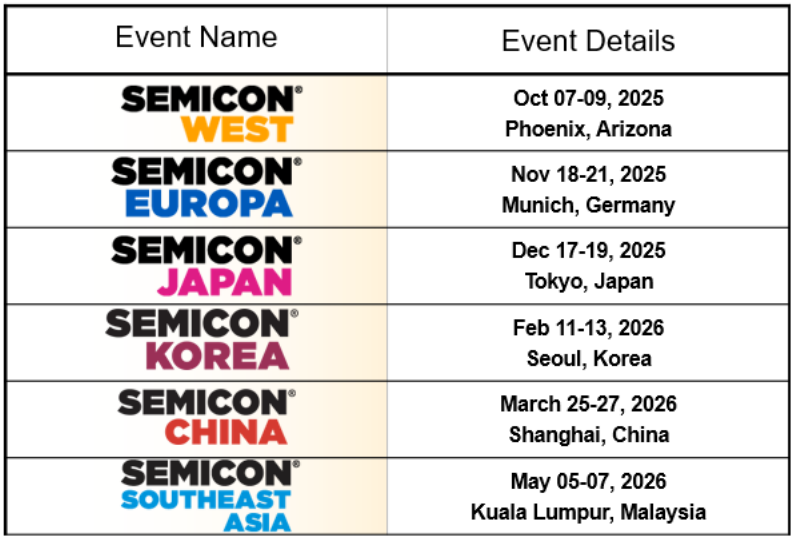
- Meeting Information
    - Last meeting
        - October 22 - Qingdao, Shandong
    - Next meeting
        - Exact date and time will be determined.
- Abolished SNARFs
    - 6767, New Standard: Test Method for GBIR, SBIR, GF3R, SFQR and SORI of Silicon Carbide Wafers by Oblique Incident Interference Method
    - 6769, New Standard: Test Method for Residual Stress of Silicon Carbide Wafers by Photoelastic Effect

Attachment: CSM China TC Chapter Nov 2025

3.3 *SEMI Staff Report*

Michelle Sun (SEMI) gave the SEMI Staff Report. Of note:

- 2025 & 2026 Calendar of Events



Event Name	Event Details
SEMICON WEST	Oct 07-09, 2025 Phoenix, Arizona
SEMICON EUROPA	Nov 18-21, 2025 Munich, Germany
SEMICON JAPAN	Dec 17-19, 2025 Tokyo, Japan
SEMICON KOREA	Feb 11-13, 2026 Seoul, Korea
SEMICON CHINA	March 25-27, 2026 Shanghai, China
SEMICON SOUTHEAST ASIA	May 05-07, 2026 Kuala Lumpur, Malaysia

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- SEMICON West 2025-2030
  - 2025—October 7-9 | Phoenix Convention Center | Phoenix, AZ
  - 2026—October 13-15 | Moscone Center | San Francisco, CA
  - 2027—October 12-14 | Phoenix Convention Center | Phoenix, AZ
  - 2028—October 10-12 | Moscone Center | San Francisco, CA
  - 2029—October 9-11 | Phoenix Convention Center | Phoenix, AZ
  - 2030—October 29-31 | Moscone Center | San Francisco, CA
- SEMI Global Standards Summit (GSS) 2025
  - **Date/Time**: Tuesday, October 7 | 1:30 PM to 5:30 PM | North Building, 200 Level, Room 229A
  - **Theme**: Future Standards for Connected & Sustainable Semiconductor Manufacturing
  - **Session Description**: The Global Standards Summit is a strategic forum dedicated to identifying standards-critical areas and advancing an industry-wide standardization roadmap for the next 3- and 7-year horizons. Building on the momentum of the inaugural Summit—which spotlighted essential topics such as environmental sustainability—this year's gathering continues that dialogue while expanding focus to include emerging challenges like supply chain traceability.
  - With increasing fragmentation across the global microelectronics supply chain driven by geopolitical and other disruptive forces, the need for unified standards is more critical than ever. This Summit provides a timely opportunity to convene, collaborate, and identify the standards that will address these challenges and foster greater industry alignment. We encourage you to join, engage, and help shape the future of standards.
- Workshops
  - SEMI Liquid Chemicals Analytical Workshop
    - Description: Focusing on recent advances in analytical methodology and instrumentation
    - Wednesday, October 8
    - 09:00-11:30 (North Bldg | Room 229B)
  - Enhancing Voltage Sag Immunity: SEMI F47 Standard Updates & Insights
    - Description: Delivering practical recommendations to enhance the SEMI F47 standard and increase tool resilience in future designs, with a focus on power quality conditions, equipment susceptibility, testing approaches, and mitigation strategies.
    - Wednesday, October 8
    - 14:30-16:30 (North Bldg | Room 229B)
  - Semiconductor Device Manufacturing in a Cleanroom (Best Practices to Improve Product Reliability and Yield) [SEMIU]
    - Description: Provides the fundamentals and thought processes to improve your production reliability & yield.
    - Thursday, October 9
    - 8:00 AM - 4:00 PM (North Bldg | 200 Level)
- Upcoming NA Meetings 2026

Event Name	Date/Venue
NA Winter Meeting	Feb 9-12, 2026 Full Virtual
NA Spring Meeting *(In conjunction with ASMC)*	May 11-14, 2026 Hilton Albany, New York
SEMICON West Meeting	October 12-15, 2026 San Francisco, California/USA

- SEMI Advanced Semiconductor Manufacturing Conference (ASMC)
  - SEMI's international technical conference for discussing solutions that improve the collective manufacturing expertise of the semiconductor industry.
  - Provides a platform for semiconductor professionals to network and learn the latest in the practical application of advanced manufacturing strategies and methodologies.
- Critical Dates for SEMI Standards Ballots 2026

2026	Ballot Submission Deadline	Voting Opens	Voting Closes
Cycle 1	December 16, 2025	January 7	February 6
Cycle 2	January 23	February 11	March 13
Cycle 3	March 5	March 18	April 17
Cycle 4	March 30	April 14	May 14
Cycle 5	May 8	May 27	June 26
…	**…**	**…**	**…**

- SEMI Standards Publications
  - Total Standards: 1,107
  - New Standards

Cycle	Designation	Title	Committee	Region
June 2025	SEMI M94	Specification for Silicon Carbide Engineered Substrates	Compound Semiconductor Materials	EU
July 2025	SEMI E194	Guide to Using a Liquid Particle Counter to Assess Particulate Surface Contamination on Critical Chamber Components and Coupons	Metrics	NA
September 2025	SEMI E195	Test Method Using Adhesive Replacement Substrates to Assess Particulate Surface Contamination on Critical Chamber Components	Metrics	NA
September 2025	SEMI E196	Guide for Equipment Edge Data Governance	Information & Control	TW
September 2025	SEMI M95	Test Method for Net Carrier Density and Resistivity of Silicon Epitaxial Layer by Capacitance-Voltage Measurements with an Evaporated Metal Schottky Diode	Silicon Wafer	JP
September 2025	SEMI T26	Specification for Electronic Supply Chain Traceability Using Distributed Ledger Technology	Traceability	NA

- Educational Courses under Development
  - {EDA} Everything You Need to Know about the SEMI Equipment Data Acquisition (EDA) Standards Suite
    - Objective: Introduce EDA standards, best practices for implementation, and addresses concerns about adoption through example use cases

        - Course Date: November 20, 2025, in conjunction with SEMICON Europa
        - Status: Confirmed, under development
    - {Subfab} Intro to Sub-fab Course
        - Objective: Gain a comprehensive understanding of SubFAB operations, including system components, facility layouts, environmental and sustainability considerations, organizational structure, safety and maintenance best practices, and incident-response preparedness within the semiconductor manufacturing ecosystem.
        - Course Date: Early 2026 (2 sessions, EU & Asia friendly)
        - Status: Under development
- Regulations & Procedure Manual
    - Regulations (Feb 20, 2024)
        - https://www.semi.org/sites/semi.org/files/2024-02/Standards%20Regulations%20February%2020%202024.pdf
    - Procedure Manual (July 7, 2025)
        - https://www.semi.org/sites/semi.org/files/2025-07/Procedure%20Manual%20July%2007%2C%202025%20v1.pdf
    - Noticeable updates:
        - Major revision to multiple Standards
        - New SNARF Form (July 2025)
        - Ballot checklist requirement for Revision to Primary Standard
- SNARF(s) Approved by GCS
    - 7357, New Standard: Specification for Failure Analysis Reporting
    - 7381, Revision to Add a New Subordinate Standard: Specification for Transforming Non-E142 XY Coordinates to SEMI E142-0125: Specification for Substrate Mapping

Attachment: Compound_Staff_HQ Report Nov 2025 v5

4 Subcommittee and Task Force Reports

4.1 *Silicon Carbide Task Force*

- New Standard published: SEMI M94, Specification for Silicon Carbide Engineered Substrates

4.2 *SiC Material and Wafer Specification TF*

- Task force reviewed SEMI M81-0611, Guide to Defects Found in Monocrystalline Silicon Carbide Substrates

5 Next Meeting and Adjournment

The next meeting is scheduled for April 14, 2026, via Web Conference. See http://www.semi.org/standards-events for the current list of events.

Adjournment: 10:12.

Respectfully submitted by:

Michelle Sun

Coordinator

SEMI North America

Phone: 408.943.7982

Email: msun@semi.org

Minutes tentatively approved by:

<Name> (<Company>), Co-chair	<Date approved>
<Name> (<Company>), Co-chair	<Date approved>

Table 14 Index of Available Attachments[#1]

Title	*Title*
Required Meeting Elements March 2024	CSM China TC Chapter Nov 2025
CSM EU TC Minutes 04012025	IC_Staff_HQ Report Oct 2025 v5
CSM_JA TC Chapter Liaison Report_October 2025_R1	

#1 Due to file size and delivery issues, attachments must be downloaded separately. A .zip file containing all attachments for these minutes is available at www.semi.org. For additional information or to obtain individual attachments, please contact [SEMI Staff Name] at the contact information above.